

## EAST Search History

## EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	218	337/333.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 17:30
S2	8	(adriana near2 sartor).in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 17:30
S3	23	elettrotec.as.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 17:33
S4	8	S2 S3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 17:35
S5	0	337/380.ccls. ((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) contact relay (feet with (base or bottom)) ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 17:37

S6	0	337/372.ccls. ((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) contact relay (feet with (base or bottom)) ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 17:37
S7	0	337/107.ccls. ((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) contact relay (feet with (base or bottom)) ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 17:37
S8	0	337/16.ccls. ((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) contact relay (feet with (base or bottom)) ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 17:37

S9	0	337/3.ccls. ((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) contact relay (feet with (base or bottom)) ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 17:38
S10	0	337/13.ccls. ((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) contact relay (feet with (base or bottom)) ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 17:38
S11	0	337/20.ccls. ((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) contact relay (feet with (base or bottom)) ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 17:38

S12	0	337/34.ccls. ((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) contact relay (feet with (base or bottom)) ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 17:38
S13	0	337/36.ccls. ((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) contact relay (feet with (base or bottom)) ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 17:38
S14	0	361/99.ccls. ((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) contact relay (feet with (base or bottom)) ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 17:39

S15	0	361/626.ccls. ((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) contact relay (feet with (base or bottom)) ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 17:39
S16	0	"361"/\$.ccls. ((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) contact relay (feet with (base or bottom)) ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 17:39
S17	0	"337"/\$.ccls. ((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) contact relay (feet with (base or bottom)) ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 17:39

S18	16	((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) contact relay (feet with (base or bottom)) ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 17:39
S19	16	"337"/\$.ccls. ((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) relay ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 18:01
S20	31	"361"/\$.ccls. ((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) relay ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 18:10
S21	252	((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) relay ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 18:12

S22	0	29/623.ccls. ((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) relay ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 18:16
S23	2	"29"/\$.ccls. ((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) relay ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 18:23
S24	0	439/620.29.ccls. ((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) relay ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 18:23
S25	0	439/620.27.ccls. ((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) relay ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 18:23
S26	0	439/620.26.ccls. ((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) relay ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 18:23

S27	0	439/250.ccls. ((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) relay ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 18:23
S28	0	439/620.33.ccls. ((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) relay ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 18:23
S29	0	439/620.34.ccls. ((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) relay ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 18:24
S30	3	"439"/\$.ccls. ((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) relay ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 18:24
S31	252	S21 relay	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 18:24



S32	51	S31 (foot or feet)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 18:24
S33	57	"1809305"   "2759066"   "3234350"   "3728659"   "4103271"   "4492946"   "4533894"   "4567458"   "4591820"   "4628295"   "4646051"   "4754251"   "4794364"   "4842419"   "4843364"   "4851807"   "4887062"   "5576683"   "5660473"   "6597274"   "6642460"   "6737952"   "6833782").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 18:27
S55	0	361/626.ccls. (relay (insulat\$3 near2 plate) contact (bimetal \$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 18:53

S56	0	337/380.ccls. (relay (insulat\$3 near2 plate) contact (bimetal \$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 18:53
S57	0	337/381.ccls. (relay (insulat\$3 near2 plate) contact (bimetal \$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 18:53
S58	0	337/373.ccls. (relay (insulat\$3 near2 plate) contact (bimetal \$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 18:53

S59	0	337/337.ccls. (relay (insulat\$3 near2 plate) contact (bimetal \$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 18:53
S60	0	337/334.ccls. (relay (insulat\$3 near2 plate) contact (bimetal \$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 18:53
S61	0	"337"/\$.ccls. (relay (insulat\$3 near2 plate) contact (bimetal \$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 18:53

S62	0	"361"/\$.ccls. (relay (insulat\$3 near2 plate) contact (bimetal \$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 18:53
S63	0	"29"/\$.ccls. (relay (insulat\$3 near2 plate) contact (bimetal \$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 18:53
S64	0	(relay (insulat\$3 near2 plate) contact (bimetal \$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 18:54
S65	3	((insulat\$3 near2 plate) contact (bimetal\$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 18:54

S68	0	((insulat\$3 near2 plate) contact (bimetal\$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) ((PCB or board or substrate) with (trac\$3 or wiring or pattern))).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 18:55
S69	11	((insulat\$3 near2 plate) contact (bimetal\$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) ((PCB or board or substrate) with (trac\$3 or wiring or pattern)) relay)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 18:55
S70	8	(adriana near2 sartor).in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 18:56
S71	23	elettrotec.as.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 18:56
S72	0	(S70 or S71) ((insulat\$3 near2 plate) contact (bimetal\$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) ((PCB or board or substrate) with (trac\$3 or wiring	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 18:56

		or pattern)) relay).clm.				
S73	0	((insulat\$3 near2 plate) contact (bimetal\$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate) (trac \$3 or wiring or pattern)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 18:56
S74	0	((insulat\$3 near2 plate) contact (bimetal\$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate) (trac \$3 or wiring or pattern))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 18:56
S75	0	337/381.ccls. ((insulat\$3 near2 plate) contact (bimetal\$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate) (trac \$3 or wiring or pattern))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 18:57

S76	1	337/380.ccls. ((insulat\$3 near2 plate) contact (bimetal\$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate) (trac \$3 or wiring or pattern))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 18:57
S77	0	337/373.ccls. ((insulat\$3 near2 plate) contact (bimetal\$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate) (trac \$3 or wiring or pattern))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 18:57
S79	0	337/334.ccls. ((insulat\$3 near2 plate) contact (bimetal\$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate) (trac \$3 or wiring or pattern))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 18:58

S80	0	337/337.ccls. ((insulat\$3 near2 plate) contact (bimetal\$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate) (trac \$3 or wiring or pattern))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 18:58
S81	63	((insulat\$3 near2 plate) contact (bimetal\$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate) (trac \$3 or wiring or pattern))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 18:58
S82	4294	((bimetal\$3 or (bi near2 metal \$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate) (trac \$3 or wiring or pattern))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 18:59
S83	1371	S82 ((hous\$3 or cas\$3 or support) with (contact or lead or terminal))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 18:59
S84	401	S83 relay	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 18:59



S85	4294	((bimetal\$3 or (bi near2 metal \$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate) (trac \$3 or wiring or pattern))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 19:00
S86	320	S85 (cover with (contact or lead or terminal))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 19:00
S87	29	S86 ((base or bottom) with (pack\$3 or pierc \$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/09/03 19:01

**EAST Search History (Interference)**

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S34	108	361/626.ccls.	US-PGPUB; USPAT; UPAD	AND	ON	2009/09/03 18:30
S35	176	337/333.ccls.	US-PGPUB; USPAT; UPAD	AND	ON	2009/09/03 18:31
S36	453	337/380.ccls.	US-PGPUB; USPAT; UPAD	AND	ON	2009/09/03 18:31
S37	226	337/373.ccls.	US-PGPUB; USPAT; UPAD	AND	ON	2009/09/03 18:39
S38	160	337/381.ccls.	US-PGPUB; USPAT; UPAD	AND	ON	2009/09/03 18:41
S39	58	337/334.ccls.	US-PGPUB; USPAT; UPAD	AND	ON	2009/09/03 18:44

S40	54	337/337.cds.	US-PGPUB; USPAT; UPAD	AND	ON	2009/09/03 18:44
S41	1128	(S34 or S35 or S36 or S37 or S38 or S39 or S40)	US-PGPUB; USPAT; UPAD	AND	ON	2009/09/03 18:45
S42	2	S41 (contact (bimetal\$3 or (bi near2 metal\$3)) (thermostat\$3 or switch) relay ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern)))	US-PGPUB; USPAT; UPAD	AND	ON	2009/09/03 18:45
S43	0	S41 (contact (bimetal\$3 or (bi near2 metal\$3)) (thermostat\$3 or switch) relay ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern))).clm.	US-PGPUB; USPAT; UPAD	AND	ON	2009/09/03 18:45
S44	37	S41 (contact (bimetal\$3 or (bi near2 metal\$3)) (thermostat\$3 or switch) (PCB or board or substrate))	US-PGPUB; USPAT; UPAD	AND	ON	2009/09/03 18:47
S45	8	S41 (contact (bimetal\$3 or (bi near2 metal\$3)) (thermostat\$3 or switch) (PCB or board or substrate)).clm.	US-PGPUB; USPAT; UPAD	AND	ON	2009/09/03 18:48
S46	5	S41 (relay (bimetal \$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or (thermal or safety) near2 switch)) (PCB or board or substrate))	US-PGPUB; USPAT; UPAD	AND	ON	2009/09/03 18:49

S47	0	S41 (relay (bimetal \$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate)).clm.	US-PGPUB; USPAT; UPAD	AND	ON	2009/09/03 18:49
S48	35	"337"/\$.ccls. (relay (bimetal\$3 or (bi near2 metal \$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate))	US-PGPUB; USPAT; UPAD	AND	ON	2009/09/03 18:49
S49	309	29/ 623.ccls.	US-PGPUB; USPAT; UPAD	AND	ON	2009/09/03 18:50
S50	0	S49 (relay (bimetal \$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate))	US-PGPUB; USPAT; UPAD	AND	ON	2009/09/03 18:50
S51	0	S49 (relay (bimetal \$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate)).clm.	US-PGPUB; USPAT; UPAD	AND	ON	2009/09/03 18:50

S52	1	"361"/\$.ccls. (relay (bimetal\$3 or (bi near2 metal \$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate)).clm.	US-PGPUB; USPAT; UPAD	AND	ON	2009/09/03 18:51
S53	0	"361"/\$.ccls. (relay (insulat\$3 near2 plate) contact (bimetal \$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate)).clm.	US-PGPUB; USPAT; UPAD	AND	ON	2009/09/03 18:52
S54	0	"337"/\$.ccls. (relay (insulat\$3 near2 plate) contact (bimetal \$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate)).clm.	US-PGPUB; USPAT; UPAD	AND	ON	2009/09/03 18:52
S66	0	"337"/\$.ccls. (relay (insulat\$3 near2 plate) contact (bimetal \$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate)).clm.	US-PGPUB; USPAT; UPAD	AND	ON	2009/09/03 18:52

S67	0	"361"/\$.ccls. (relay (insulat\$3 near2 plate) contact (bimetal \$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate)).clm.	US-PGPUB; USPAT; UPAD	AND	ON	2009/09/03 18:52
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9/ 3/ 2009 7:01:52 PM

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\ 10 599622 RCE Amendment.wsp